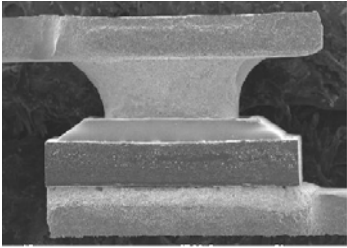
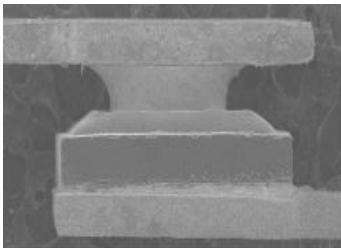
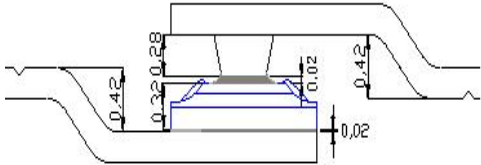
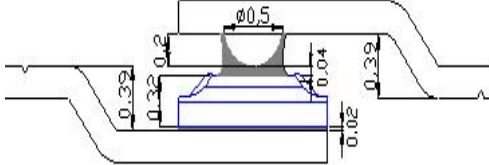


SMA (HER GPP) 1A series surface mount rectifiers(HS1G) comparison report

Prepared by Owen Wang
Checked by Owen Wang
Approved by Quayer Chen
Issued date at 4th Sep, 2012
Reversion for A

Comparison report (HS1G)

Inner construction picture/diagram:

	Old	New	Result
X-ray			Dimple shape has changed.
Diagram			

Inner construction dimension:

Item	Old	New	Result
Lead-frame	Down set(mm)	0.42	Dimple dimension has changed.
	Dimple diameter(mm)	Φ0.38	
	Dimple height(mm)	0.28	
Free gap between dimple and die surface(mm)	0.02	0.04	

Material information summary:

	Old	New	Result
Solder wafer(mm)	1.2 x 0.05	1.2 x 0.05	No change

Comparison report (HS1G)

Electrical characteristics summary:

Typical data	Old	New	Result
Maximum Instantaneous Forward Voltage VF < 1.3V @ 1.0A	0.921	0.928	Electrical characteristics are complying with TSC specification.
Maximum Recurrent Peak Reverse Voltage VRRM > 400V @ 5.0uA	545	535	
Maximum DC Reverse Current IR < 5.0uA @ 400V	0.008	0.002	
Maximum Forward Surge Current, 8.3ms sigle half sine-wave IFSM > 30A	50	50	
Typical Thermal Resistance Rth j-A = 70.0°C/W (Note)	70	70	

Note:

Mounted on P.C.Board with 0.2" x 0.2" (5mm x 5mm) copper pad area.

Production Part Approval - Material, Performance Test Results Discrete Semiconductor Component Qualification Plan

Customer P/N :	HS1G	Product Engineer :	Meifang
Customer Spec. # :	N/A	General Specification :	
Supplier Name :	Taiwan Semiconductor Corp.	Supplier Manufacturing Site :	YEW
Supplier Generic P/N :	SMA 1Amps surface mount rectifiers	Required PPAP Submission Date :	14-Sep-11
Supplier Internal P/N :	HS1A thru HS1M	Family Type :	HER GPP
Reason for Qual. :	Dimple shape/dimension change		

Item	Test	Test Condition	Exceptions	Est. Start	Est. Comp.	# Lots	S.S.	Remarks
1	Electrical Test	Electrical characterization	@25°C	2011/9/4	2011/9/4	ALL	260	ACC
2	External Visual	Inspect device construction, marking and workmanship	N/A	2011/9/4	2011/9/4	ALL	260	ACC
3	Parameter Verification	Electrical characterization	@25/150°C	2011/9/4	2011/9/4	1	10	ACC
4	Pre-conditioning	Per specification	N/A	2011/9/4	2011/9/14	1	308	ACC
5	H.3T.R.B	Ta = 85 ± 2°C, R.H = 85 ± 5% VR = 80%	168hrs	2011/9/15	2011/9/23	1	77	ACC
6	H.T.R.B.	80% Rated VR (T=150°C)	168hrs	2011/9/4	2011/9/12	1	77	ACC
7	Soldering Heat	Ta = 260 ± 5°C	10secs	2011/9/4	2011/9/4	1	30	ACC
8	Temperature Cycle	-55°C/15Min, 150°C/15Min, 25°C/5Min (Transfer)	100cycles	2011/9/15	2011/9/23	1	77	ACC
9	Autoclave	Ta = 121 ± 2°C 15Psig	96hrs	2011/9/15	2011/9/23	1	77	ACC
10	Intermittent Operating Life	On/5min, Off/5min	2520cycles	2011/9/15	2011/9/23	1	77	ACC
11	Humidity	Ta = 85 ± 2°C, R.H = 85 ± 5%	168hrs	2011/9/15	2011/9/23	1	77	ACC
12	Low Temperature Storage	Ta = -55 ± 3°C	168hrs	2011/9/15	2011/9/23	1	77	ACC
13	High Temperature Storage	Ta = 150(+10/-0)°C	168hrs	2011/9/15	2011/9/23	1	77	ACC
14	Solderability	Ta = 245 ± 5°C	5secs	2011/9/15	2011/9/16	1	10	ACC
15	DPA	Per specification	N/A	2011/9/15	2011/9/16	1	2	ACC
16								
17								

Comment :

Prepared by :	Haiyen Liu	Approved by :	Cuihejun
Date :	23-Sep-11	Date :	25-Sep-11
Title :	Hi-rel supervisor	Title :	QA leader